



From layout to chips

Add-On Services



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From layout to chips

The Add-On Services purpose

Providers:
Academics /
Industrials



Promote

mycmp.fr/services/Add-on

Important IP Blocks
Design Expertise

Software & Design Routines
Test Bench

Characterization facility
IC Inspection & Repairs

System Level services
Packaging Services

Look for
solutions

R& D Institute /
Website Visitors
Worldwide Users

- **Provide visibility** to specific and useful services

→ Visibility for the providers

→ Unique service catalog for the users

- **Consolidate CMP** as a core provider of solutions for prototyping services



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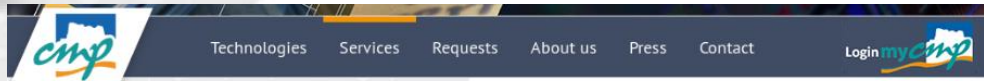
European
Commission

Horizon 2020
European Union funding
for Research & Innovation



From layout to chips

Add-On Services: browser



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Add-On Services

You're interested in highlighting a specific industrial service, a design expertise, an important thesis, an innovative IP, a characterization facility, a process or a methodology you improved or a specific/original tool you created?

|| CMP is currently looking for industrials and academics to grow the Add-On Services showcase

This webpage is a showcase meant to **highlight specific services** from **companies or academics** in order to provide **advanced and qualitative prototypes** services to our R&D community.

You'll find services completing our prototyping offers: from advanced design services to innovative packaging solutions, discover here original services that may improve your prototyping experience!

CMP takes no fee in these services and does not act as an intermediary between the provider and the user. The goal of this showcase is solely to develop the R&D community in microelectronics giving visibility to advanced and original processes reviewed by CMP.

Contact us

Jeremy PERRET

ALL

- Software
- Design services
- IPs
- Specific Packaging
- System level services
- IC Inspection & Repair
- Tests

Intento Design Software RESPONSIVE EDA FOR ANALOG IP	VLC Photonics Design services 	ALGODONE IPs 	HCM SYSTREL Specific Packaging HCM.SYSTREL	LIP6/CORLIOS Software
Hiventive Software 	FastFieldSolvers S.R.L. Software 	NoiseTech Microwaves Tests 	Sencio Specific Packaging functional packaging center	ICALps Design services
Synergie Cad PSC Specific Packaging Power SEMICONDUCTORS	ID MOS Design services ID MOS	ReRouting LLC Design services 	Ironwood Electronics Tests 	APTASIC SA Tests supplying customized ICs
RFIC-Lab Design services 	GIP-CNFM Software 			

Dedicated webpage

Categories of Services

Companies / Labs already in AOS



From layout to chips

Illustration

CMP Home > Services > Add-On Services > Synergie Cad PSC


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Company name

Synergie Cad PSC

Company or lab logo

CONTACT



SYNERGIE CAD PSC
PARTNER SEMICONDUCTORS

Contact the provider :

URL : <http://www.synergie-cad.fr>

DOCUMENTATION :

Direct contact link

Easy access on CMP website

Main services

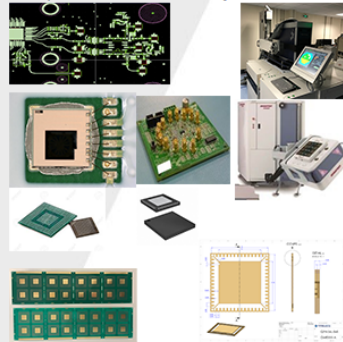
Specific Packaging

|| Synergie CAD Partner SemiConductors (Synergie Cad PSC)

, created in 2000 as a subsidiary of Synergie Cad Group, has a unique offer in the supply of services in Electronics and Microelectronics industrialization and production. On top of Development and fabrication of PCB's, its traditional business line, Synergie Cad PSC has developed around Semiconductors industrialization and production services with our In-House equipments and competences in IC's Packaging, IC's Test & Product Engineering, IC's qualification / reliability, Semiconductors supply chain and Electronic boards & Probe cards (Design, fabrication, Assembly).

Direct link to company or lab website

Focus on: Plastic packages



One of our main specificities is to offer the possibility of fast-run plastic-fully moulded packages for prototyping and small series purposes. The following packaging types are available in standard leadframes in full plastic: - QFN 32/36/48/76 - DIP 8/14/16/18 - SOIC 14/16/20/24/28 - QFP 64/100 - BGA 200balls This may also include capabilities in thermal and electrical simulations. Small and mid-series production roadmap is also

Service description

available for BGA, QFN, and QFP packages (as below):

INTERNAL PLASTIC LINE Roadmap

Focus on: RF & MMW test

Another of our main specificities is to offer capabilities in RF & Millimetric Wave testing and characterization, up to 100GHz.

Illustrations of services

Contributions from academics



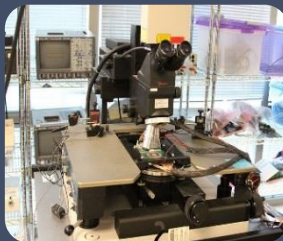
Intellectual Property

- Academics who work on specific IPs can promote them.



Design expertise

- Academics can have a design expertise and help designing chips.



Testing

- Academics might have advanced machines to test chips.

Do not hesitate to make suggestions, we are open to new ideas !

AOS Community IP sharing

- IP blocks are desirable **to ease and speed up design**
 - **Affordable access to IP** for R&D purposes
 - **Non qualified but tested IP blocks** could be shared through CMP !
 - CMP manages the collection of IPs that users are ready to share
 - Terms and conditions:
 - Free of charge**, rewards with references or coauthoring or others
- Note: IP sharing is only possible through CMP** in agreement with confidentiality licenses (CLA) !!!

AOS Terms and Conditions

- Service **free of charge** for providers and users !
- Only **original** and **specific** services to serve R&D and prototyping purposes
- Only a **publicity agreement** to be signed
- Users and providers are **directly interacting**
- Services proposal to be submitted within a **specific frame**